

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Canceled)
2. (Currently Amended) A ferroelectric element manufacturing method comprising ~~the steps of~~ :
 - forming a buffer layer, which also functions as a sacrificial layer, on a single crystal substrate;
 - forming a ferroelectric element on the buffer layer;
 - separating the ferroelectric element and the single crystal substrate; and
 - arranging the ferroelectric element that was separated from the single crystal substrate on any substrates [-], wherein
the separating of the ferroelectric element and the single crystal substrate includes:
 - pasting a supportable material for supporting the ferroelectric element over a top face of the ferroelectric element; and
 - separating the ferroelectric element from the single crystal substrate by etching the buffer layer, after the supportable material has been pasted, and
 - the arranging of the ferroelectric element that was separated from the single crystal substrate on any substrates includes:

applying adhesive over a top face of any substrates and a bottom face of the ferroelectric element, and joining the separated ferroelectric element to any substrates; and

removing the supportable material that was pasted on the top face of the ferroelectric element.

3. – 10. (Cancelled)

11. (Currently Amended) An oscillator comprising:

an electrode for applying electrical signals, formed on ~~the~~ a piezoelectric thin film of ~~the~~ a surface acoustic wave element ~~according to claim 7~~ or on a protective film that is provided on the piezoelectric thin film, the electrode generating surface acoustic waves in the piezoelectric thin film by using the applied electrical signals; and

an oscillating circuit equipped with an electrode for resonance and a transistor, the oscillating circuit being formed on the piezoelectric thin film or the protective film, and resonating specific frequency components, or a specific band of frequency components, of the surface acoustic waves that were generated by the electrode for applying electrical signals [-], wherein

the surface acoustic wave element includes a piezoelectric thin film, which comprises a ferroelectric film obtained by a ferroelectric film manufacturing method, and

the ferroelectric film manufacturing method includes:

forming a buffer layer, which also functions as a sacrificial layer, on a single crystal substrate;

forming a ferroelectric film on the buffer layer;
separating the ferroelectric film and the single crystal substrate; and
arranging the ferroelectric film that was separated from the single crystal
substrate on any substrates.

12. (Currently Amended) An oscillator comprising:
an electrode for applying electrical signals, formed on ~~the~~ a piezoelectric thin film
of ~~the~~ a surface acoustic wave element ~~according to claim 8~~ or on a protective film that
is provided on the piezoelectric thin film, the electrode generating surface acoustic
waves in the piezoelectric thin film by using the applied electrical signals; and
an oscillating circuit equipped with an electrode for resonance and a transistor,
the oscillating circuit being formed on the piezoelectric thin film or the protective film,
and resonating specific frequency components, or a specific band of frequency
components, of the surface acoustic waves that were generated by the electrode for
applying electrical signals [-] , wherein

the surface acoustic wave element includes a piezoelectric element, which
comprises a ferroelectric element obtained by a ferroelectric element manufacturing
method, and

the ferroelectric element manufacturing method includes:
forming a buffer layer, which also functions as a sacrificial layer, on a
single crystal substrate;
forming a ferroelectric element on the buffer layer;
separating the ferroelectric element and the single crystal substrate; and

arranging the ferroelectric element that was separated from the single crystal substrate on any substrates.

13. (Previously Presented) An electronic circuit comprising:
the oscillator according to claim 11; and
an electrical signal supply element, which applies electrical signals to the electrode for applying electrical signals, provided in the oscillator;
the electronic circuit having the functions of selecting specific frequency components from frequency components of electrical signals, or converting it to specific frequency components, and modulating electrical signals in a predetermined manner, demodulating it in a predetermined manner, or detecting waves in a predetermined manner.

14. (Previously Presented) An electronic circuit comprising:
the oscillator according to claim 12; and
an electrical signal supply element, which applies electrical signals to the electrode for applying electrical signals, provided in the oscillator;
the electronic circuit having the functions of selecting specific frequency components from frequency components of electrical signals, or converting it to specific frequency components, and modulating electrical signals in a predetermined manner, demodulating it in a predetermined manner, or detecting waves in a predetermined manner.

15. – 16. (Canceled)

17. (Previously Presented) An electronic apparatus comprising the oscillator according to claim 11.

18. (Previously Presented) An electronic apparatus comprising the oscillator according to claim 12.

19. (Previously Presented) An electronic apparatus comprising the electronic circuit according to claim 13.

20. (Previously Presented) An electronic apparatus comprising the electronic circuit according to claim 14.